



# SOT1828-3

CFM2F, ceramic, flange mount flat package; 2 terminals; 9.78 mm x 10.16 mm x 3.66 mm body

12 June 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	CFM2F
<b>Package style descriptive code</b>	CFM (ceramic flange mount)
<b>Package body material type</b>	C (ceramic)
<b>Mounting method type</b>	F (flange mount)
<b>Issue date</b>	05-03-2018
<b>Manufacturer package code</b>	98ASA01061D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.03	10.16	10.29	mm
package width	9.7	9.78	9.86	mm
package height	3.18	3.66	4.14	mm
actual quantity of termination	-	2	-	



2 Package outline

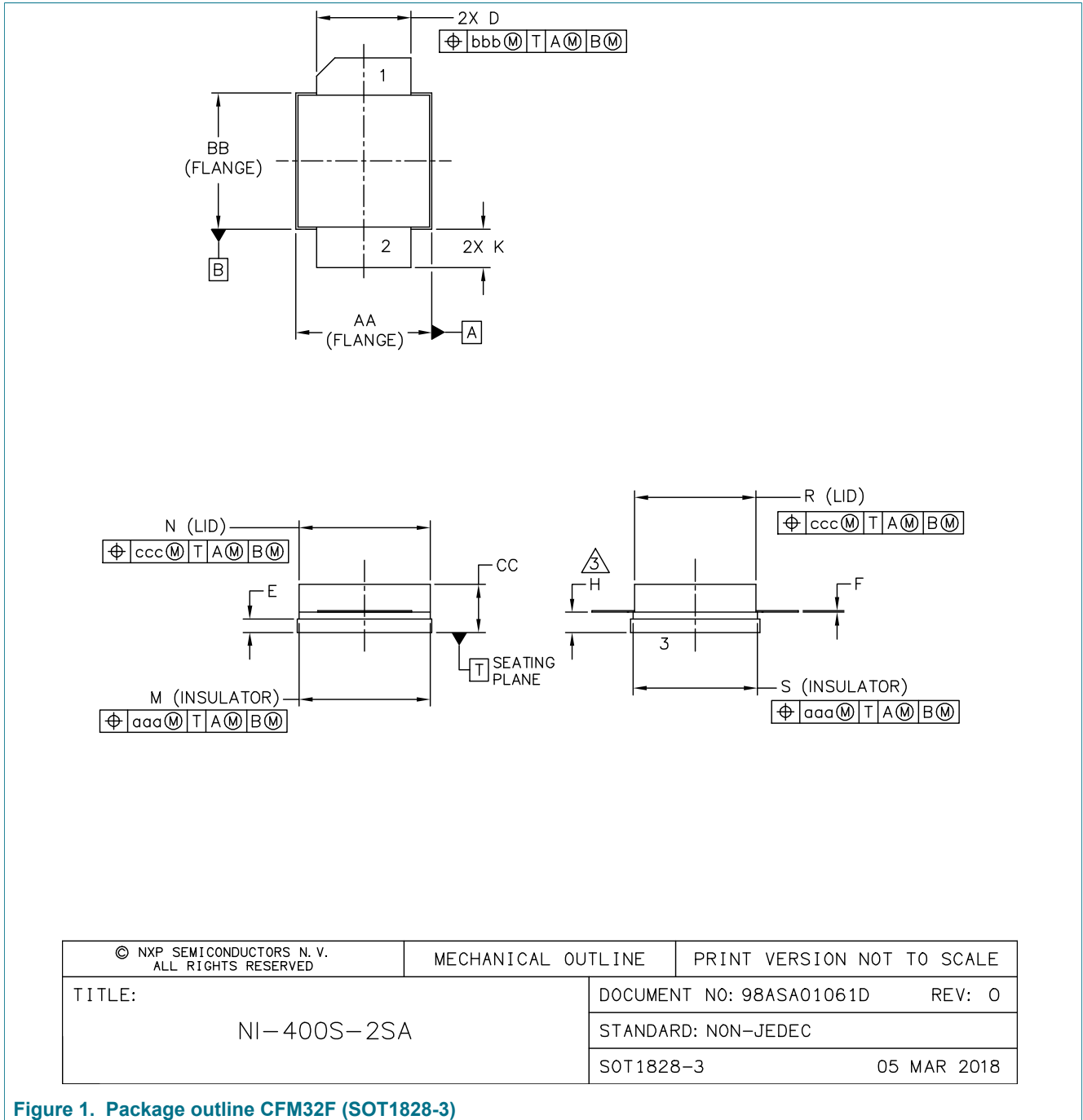


Figure 1. Package outline CFM32F (SOT1828-3)

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NOTES:

- 1. CONTROLLING DIMENSION: INCH
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- 3. DIMENSION H IS MEASURED .030 INCH (0.762 MM) AWAY FROM THE FLANGE TO CLEAR THE EPOXY FLOW OUT REGION PARALLEL TO DATUM B.
- 4. INPUT & OUTPUT LEADS (PIN 1 & 2) MAY HAVE SMALL FEATURES SUCH AS SQUARE HOLES OR NOTCHES FOR MANUFACTURING CONVENIENCE.

BB	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.395	.405	10.03	10.29	aaa	.005		0.13	
DIM	.382	.388	9.70	9.86	bbb	.010		0.25	
CC	.125	.163	3.18	4.14	ccc	.015		0.38	
D	.275	.285	6.98	7.24					
E	.031	.041	0.79	1.04					
F	.004	.006	0.10	0.15					
H	.057	.067	1.45	1.70					
K	.0995	.1295	2.53	3.29					
M	.395	.405	10.03	10.29					
N	.385	.395	9.78	10.03					
R	.355	.365	9.02	9.27					
S	.365	.375	9.27	9.53					

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	STANDARD: NON-JEDEC	
	SOT1828-3	05 MAR 2018

Figure 2. Package outline note CFM32F (SOT1828-3)

### 3 Legal information

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**Contents**

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1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....4